
Semiconductor devices - Mechanical and climatic test methods - Part 33:
Accelerated moisture resistance, unbiased autoclave (IEC 60749-33:2004)

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English version

**Semiconductor devices –
Mechanical and climatic test methods
Part 33: Accelerated moisture resistance –
Unbiased autoclave
(IEC 60749-33:2004)**

Dispositifs à semiconducteurs –
Méthodes d'essais mécaniques
et climatiques
Partie 33: Résistance à l'humidité
accélérée –
Autoclave sans polarisation
(CEI 60749-33:2004)

Halbleiterbauelemente –
Mechanische und klimatische
Prüfverfahren
Teil 33: Beschleunigte Verfahren für
Feuchtebeständigkeit –
Autoclave ohne elektrische
Beanspruchung
(IEC 60749-33:2004)

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Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Cyprus, Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, Netherlands, Norway, Poland, Portugal, Slovakia, Slovenia, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 47/1737/FDIS, future edition 1 of IEC 60749-33, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60749-33 on 2004-04-01.

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 2005-01-01
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2007-04-01

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60749-33:2004 was approved by CENELEC as a European Standard without any modification.

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE Where an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60749-24	- 1)	Semiconductor devices - Mechanical and climatic test methods Part 24: Accelerated moisture resistance - Unbiased HAST	EN 60749-24	2004 2)

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1) Undated reference.

2) Valid edition at date of issue.

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INTERNATIONAL STANDARD

IEC 60749-33

First edition
2004-03

Semiconductor devices – Mechanical and climatic test methods –

Part 33: Accelerated moisture resistance – Unbiased autoclave

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International Electrotechnical Commission, 3, rue de Varembe, PO Box 131, CH-1211 Geneva 20, Switzerland
Telephone: +41 22 919 02 11 Telefax: +41 22 919 03 00 E-mail: inmail@iec.ch Web: www.iec.ch



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES –
MECHANICAL AND CLIMATIC TEST METHODS –

Part 33: Accelerated moisture resistance –
Unbiased autoclave

FOREWORD

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International Standard IEC 60749-33 has been prepared by IEC technical committee 47: Semiconductor devices.

This standard cancels and replaces IEC/PAS 62172 published in 2000. This first edition constitutes a technical revision.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/1737/FDIS	47/1747/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until 2007. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

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